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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 6x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c771t-i-so

TABLE 1-1: PIC16C717/770/771 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0	RA0	ST	CMOS	Bi-directional I/O
	AN0	AN		A/D input
RA1/AN1/LVDIN	RA1	ST	CMOS	Bi-directional I/O
	AN1	AN		A/D input
	LVDIN	AN		LVD input reference
RA2/AN2/VREF-/VRL	RA2	ST	CMOS	Bi-directional I/O
	AN2	AN		A/D input
	VREF-	AN		Negative analog reference input
	VRL		AN	Internal voltage reference low output
RA3/AN3/VREF+/VRH	RA3	ST	CMOS	Bi-directional I/O
	AN3	AN		A/D input
	VREF+	AN		Positive analog reference input
	VRH		AN	Internal voltage reference high output
RA4/T0CKI	RA4	ST	OD	Bi-directional I/O
	T0CKI	ST		TMR0 clock input
RA5/$\overline{MCLR}$/VPP	RA5	ST		Input port
	$\overline{MCLR}$	ST		Master clear
	VPP	Power		Programming voltage
RA6/OSC2/CLKOUT	RA6	ST	CMOS	Bi-directional I/O
	OSC2		XTAL	Crystal/resonator
	CLKOUT		CMOS	FOSC/4 output
RA7/OSC1/CLKIN	RA7	ST	CMOS	Bi-directional I/O
	OSC1	XTAL		Crystal/resonator
	CLKIN	ST		External clock input/ER resistor connection
RB0/AN4/INT	RB0	TTL	CMOS	Bi-directional I/O**(1)**
	AN4	AN		A/D input
	INT	ST		Interrupt input
RB1/AN5/$\overline{SS}$	RB1	TTL	CMOS	Bi-directional I/O**(1)**
	AN5	AN		A/D input
	$\overline{SS}$	ST		SSP slave select input
RB2/SCK/SCL	RB2	TTL	CMOS	Bi-directional I/O**(1)**
	SCK	ST	CMOS	Serial clock I/O for SPI
	SCL	ST	OD	Serial clock I/O for I^2C
RB3/CCP1/P1A	RB3	TTL	CMOS	Bi-directional I/O**(1)**
	CCP1	ST	CMOS	Capture 1 input/Compare 1 output
	P1A		CMOS	PWM P1A output
RB4/SDI/SDA	RB4	TTL	CMOS	Bi-directional I/O**(1)**
	SDI	ST		Serial data in for SPI
	SDA	ST	OD	Serial data I/O for I^2C
RB5/SDO/P1B	RB5	TTL	CMOS	Bi-directional I/O**(1)**
	SDO		CMOS	Serial data out for SPI
	P1B		CMOS	PWM P1B output

Note 1: Bit programmable pull-ups.

2: Only in PIC16C770/771 devices.

2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these PIC® microcontrollers. Each block (Program Memory and Data Memory) has its own bus, so that concurrent access can occur.

Additional information on device memory may be found in the PICmicro™ Mid-Range MCU Family Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16C717/770/771 devices have a 13-bit program counter capable of addressing an 8K x 14 program memory space. The PIC16C717 and the PIC16C770 have 2K x 14 words of program memory. The PIC16C771 has 4K x 14 words of program memory. Accessing a location above the physically implemented address will cause a wrap-around.

The RESET vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK OF THE PIC16C717 AND PIC16C770

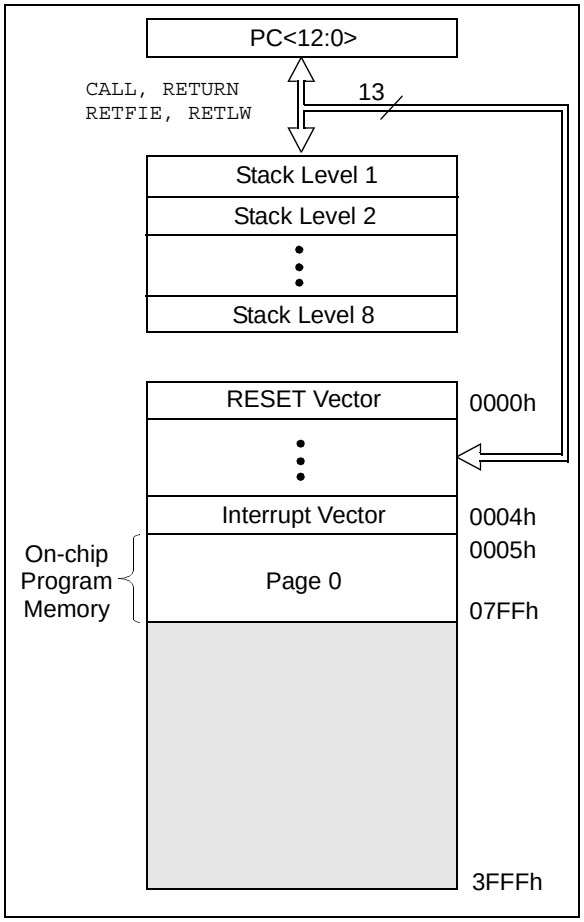
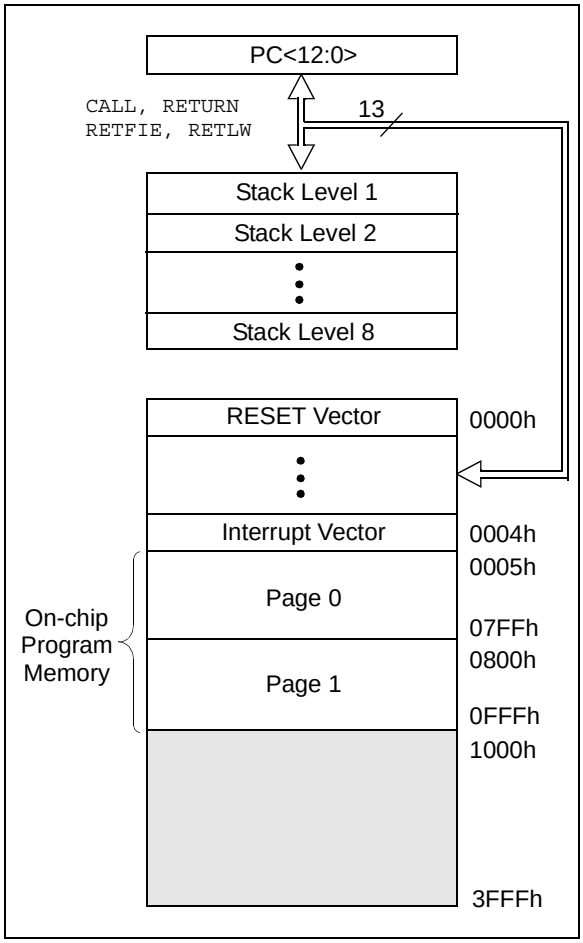


FIGURE 2-2: PROGRAM MEMORY MAP AND STACK OF THE PIC16C771



2.2 Data Memory Organization

The data memory is partitioned into multiple banks, which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1	RP0	(STATUS<6:5>)

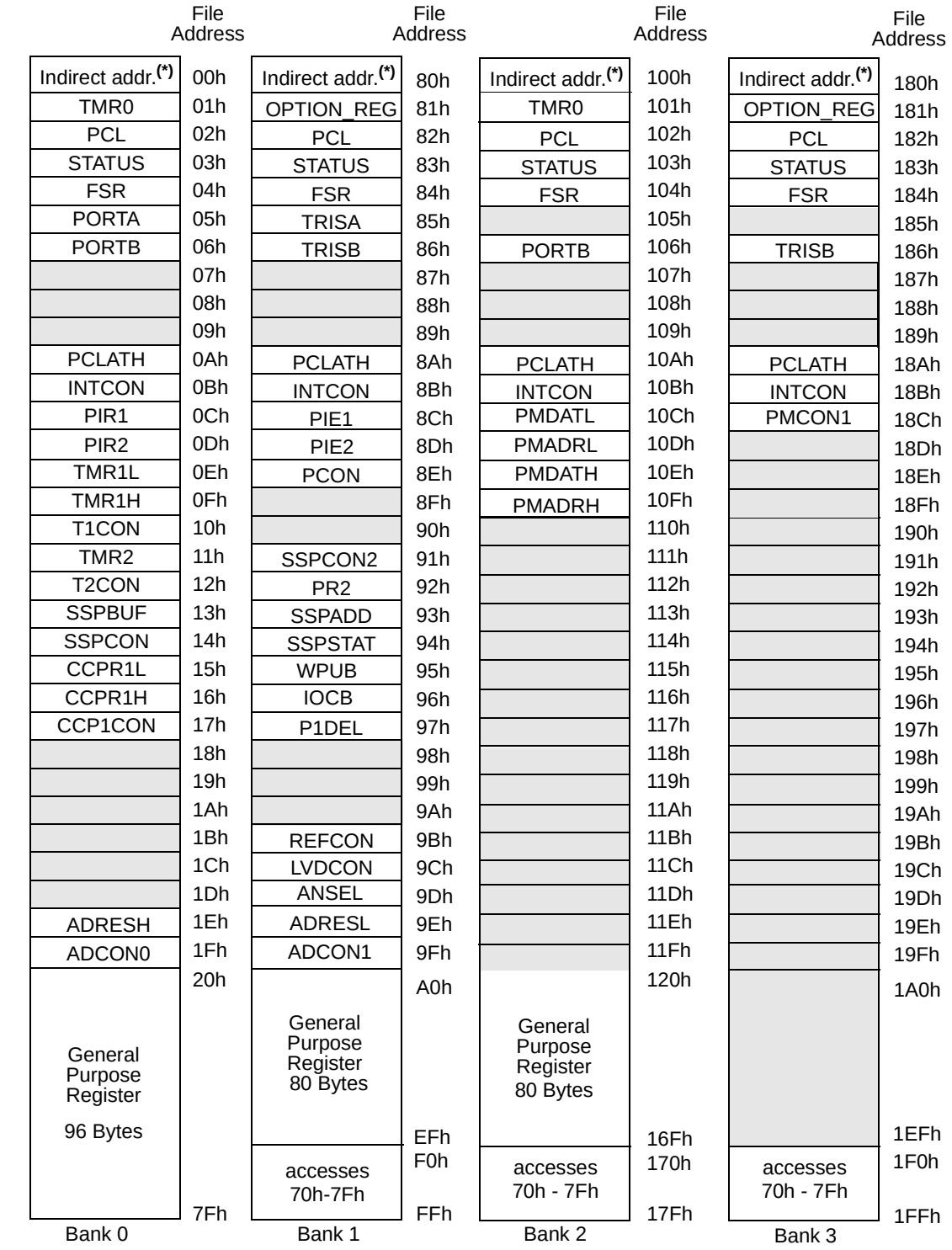
= 00 → Bank0
= 01 → Bank1
= 10 → Bank2
= 11 → Bank3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain special function registers. Some frequently used special function registers from one bank are mirrored in another bank for code reduction and quicker access.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly, through the File Select Register FSR.

FIGURE 2-3: REGISTER FILE MAP



2.2.2.4 PIE1 REGISTER

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

REGISTER 2-4: PERIPHERAL INTERRUPT ENABLE REGISTER 1 (PIE1: 8Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit 7							bit 0

bit 7 **Unimplemented:** Read as ’0’

bit 6 **ADIE:** A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5-4 **Unimplemented:** Read as ’0’

bit 3 **SSPIE:** Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2 **CCP1IE:** CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

bit 1 **TMR2IE:** TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0 **TMR1IE:** TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

2.2.2.6 PIE2 REGISTER

This register contains the individual enable bits for the SSP bus collision and low voltage detect interrupts.

REGISTER 2-6: PERIPHERAL INTERRUPT ENABLE REGISTER 2 (PIE2: 8Dh)

R/W-0	U-0	U-0	U-0	R/W-0	U-0	U-0	U-0
LVDIE	—	—	—	BCLIE	—	—	—
bit 7							bit 0

bit 7 **LVDIE:** Low Voltage Detect Interrupt Enable bit
1 = LVD Interrupt is enabled
0 = LVD Interrupt is disabled

bit 6-4 **Unimplemented:** Read as '0'

bit 3 **BCLIE:** Bus Collision Interrupt Enable bit
1 = Bus Collision interrupt is enabled
0 = Bus Collision interrupt is disabled

bit 2-0 **Unimplemented:** Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

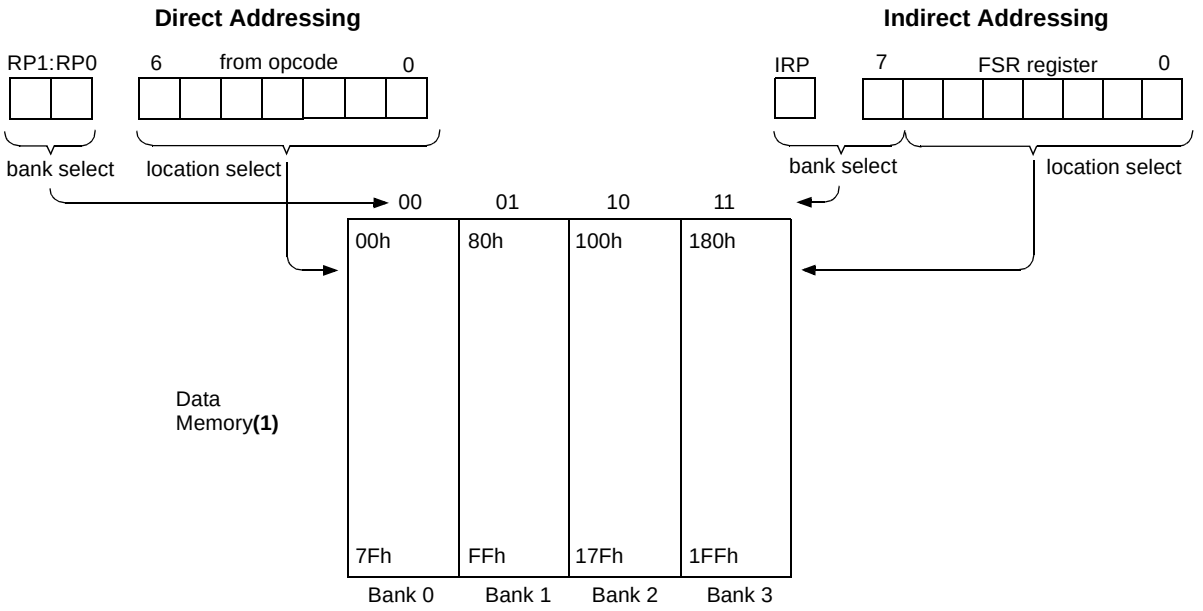
A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-1.

EXAMPLE 2-1: How to Clear RAM Using Indirect Addressing

```
        movlw   0x20    ;initialize pointer
        movwf   FSR     ;  to RAM
NEXT    clrf    INDF    ;clear INDF register
        incf    FSR     ;inc pointer
        btfss   FSR,4   ;all done?
        goto    NEXT    ;NO, clear next
CONTINUE
        :               ;YES, continue
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-5.

FIGURE 2-5: DIRECT/INDIRECT ADDRESSING



Note 1: For register file map detail see Figure 2-3.

9.1 SPI Mode

The SPI mode allows eight bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO)
- Serial Data In (SDI)
- Serial Clock (SCK)

Additionally, a fourth pin may be used when in a Slave mode of operation:

- Slave Select ($\overline{SS}$)

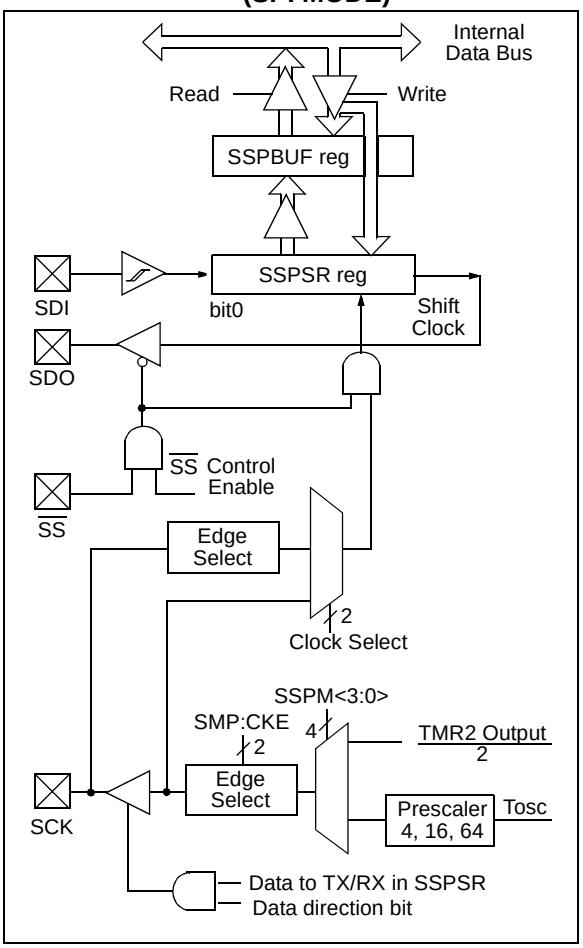
9.1.1 OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPCON<5:0> and SSPSTAT<7:6>). These control bits allow the following to be specified:

- Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Data input sample phase (middle or end of data output time)
- Clock edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

Figure 9-1 shows the block diagram of the MSSP module when in SPI mode.

FIGURE 9-1: MSSP BLOCK DIAGRAM (SPI MODE)



The MSSP consists of a transmit/receive Shift Register (SSPSR) and a Buffer Register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the eight bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit, BF (SSPSTAT<0>), and the interrupt flag bit, SSPIF (PIR1<3>), are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

FIGURE 9-5: SPI SLAVE MODE WAVEFORM (CKE = 0)

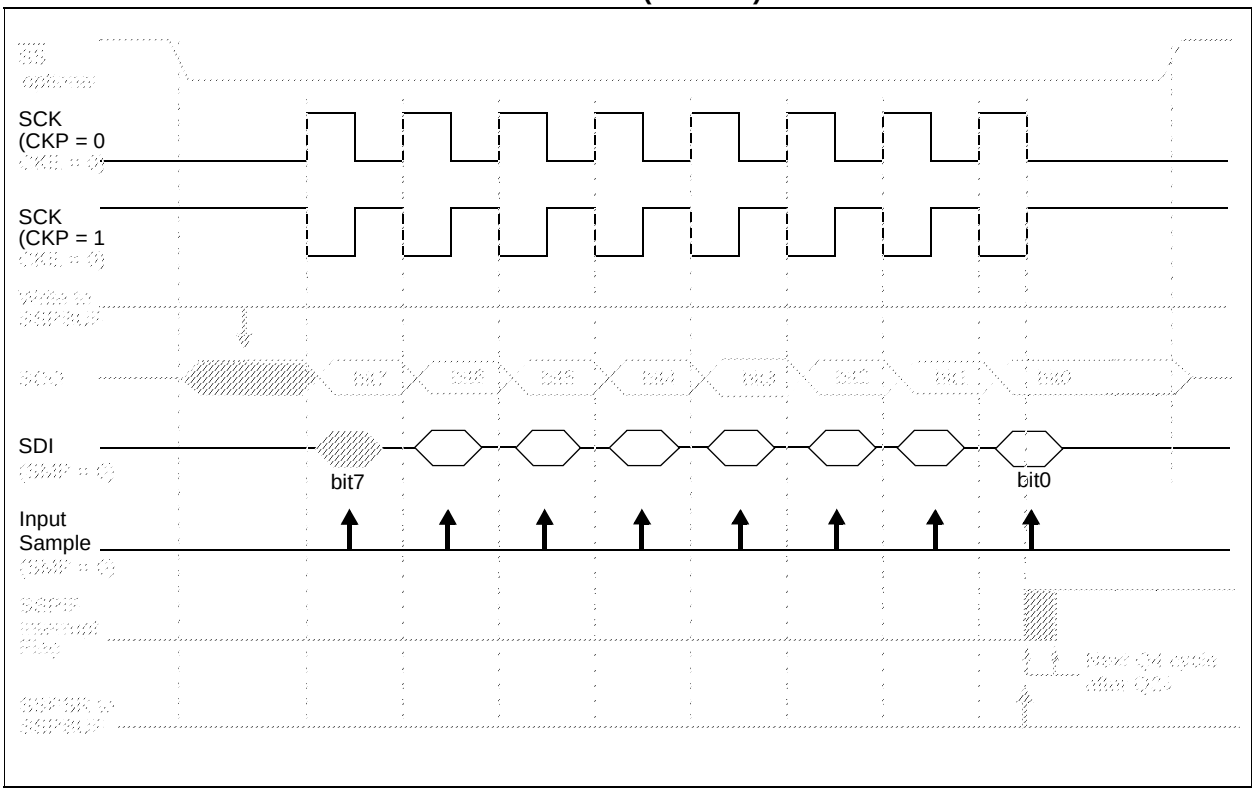
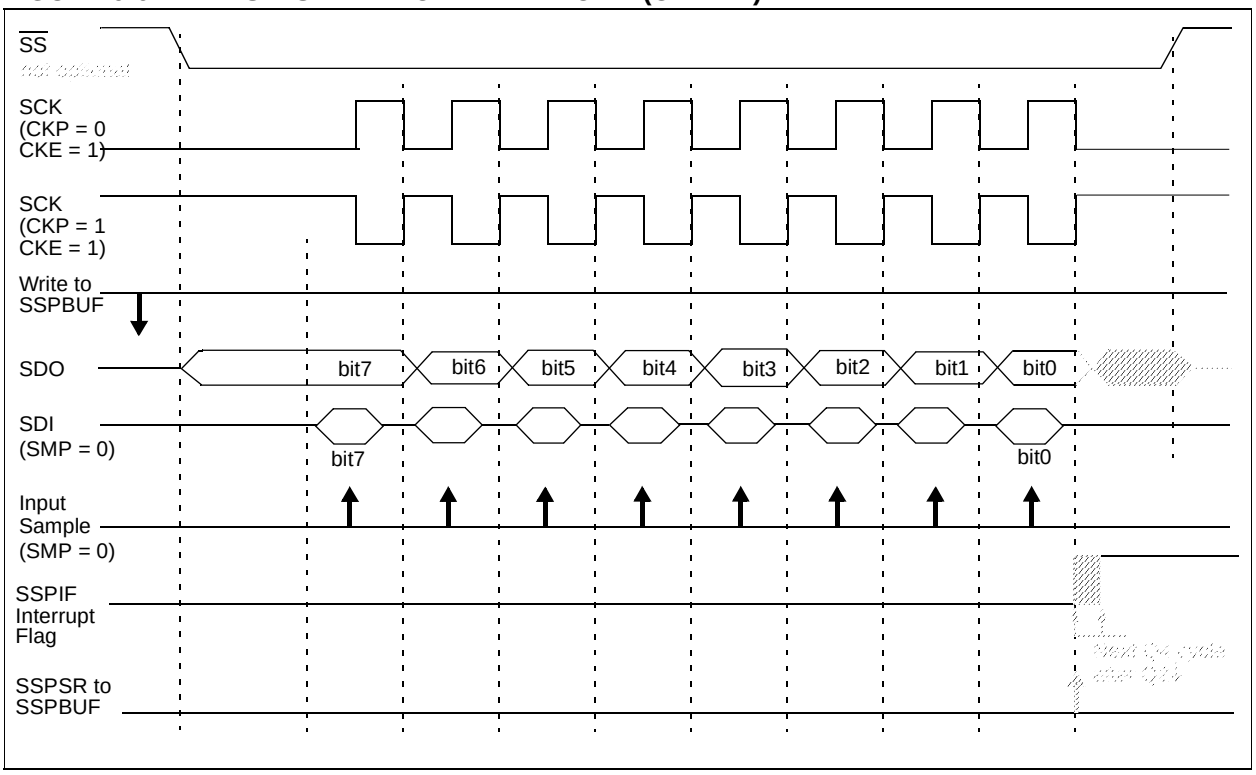


FIGURE 9-6: SPI SLAVE MODE WAVEFORM (CKE = 1)



9.2.13 I²C MASTER MODE RECEPTION

In Master-receive mode, the first byte transmitted contains seven bits of address data and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate receive. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received eight bits at a time. After each byte is received, an Acknowledge bit is transmitted. The START condition indicates the beginning of a transmission. The master-receiver terminates slave transmission by responding to the last byte with a NACK Acknowledge and follows this with a STOP condition to indicate to other masters that the bus is free.

Master mode reception is enabled by setting the receive enable bit, RCEN (SSPCON2<3>), immediately following the Acknowledge sequence.

Note:	The MSSP Module must be in an IDLE STATE before the RCEN bit is set or the RCEN bit will be disregarded.

The baud rate generator begins counting, and on each rollover, the state of the SCL pin changes (high to low/ low to high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the following events occur:

- The receive enable bit is automatically cleared.
- The contents of the SSPSR are loaded into the SSPBUF.
- The BF flag is set.
- The SSPIF is set.
- The baud rate generator is suspended from counting, holding SCL low.

The SSP is now in IDLE state, awaiting the next command. When the buffer is read by the CPU, the BF flag is automatically cleared. The user can then send an Acknowledge bit at the end of reception by clearing the ACKDT bit (SSPCON2<5>) and setting the Acknowledge sequence enable bit, ACKEN (SSPCON2<4>).

A typical receive sequence would go as follows:

a) The user generates a START Condition by setting the START enable bit (SEN) in SSPCON2.
b) SSPIF is set at the completion of the START sequence.
c) The user resets the SSPIF bit and loads the SSPBUF with seven bits of address in the MSbs and the LSb (R/$\overline{W}$ bit) set to '1' for receive.
d) Address and R/$\overline{W}$ is shifted out the SDA pin until all eight bits are transmitted.
e) The MSSP Module shifts in the $\overline{ACK}$ bit from the slave device, and writes its value into the SSPCON2 register (SSPCON2<6>).
f) The module generates an interrupt at the end of the ninth clock cycle by setting SSPIF.
g) The user resets the SSPIF bit and sets the RCEN bit to enable reception.
h) DATA is shifted into the SDA pin until all eight bits are received.
i) The MSSP module sets the SSPIF bit and clears the RCEN bit at the falling edge of the eighth clock.
j) The user resets the SSPIF bit and sets the ACKDT bit to '0' ($\overline{ACK}$), if another byte is anticipated. Otherwise, the ACKDT bit is set to '1' (NACK) to terminate reception. The user sets ADKEN to start the Acknowledge sequence.
k) The MSSP module sets the SSPIF bit at the completion of the Acknowledge.
l) If a NACK was sent in step (j), then the user proceeds with step (m). Otherwise, reception continues by repeating steps (g) through (j).
m) The user generates a STOP condition by setting the STOP enable bit PEN in SSPCON2.
n) SSPIF is set when the STOP condition is complete.

9.2.13.1 BF STATUS FLAG

In receive operation, BF is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared by hardware when SSPBUF is read.

9.2.13.2 SSPOV STATUS FLAG

In receive operation, SSPOV is set when eight bits are received into the SSPSR and the BF flag is already set from a previous reception.

9.2.13.3 WCOL STATUS FLAG

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

9.2.14 ACKNOWLEDGE SEQUENCE TIMING

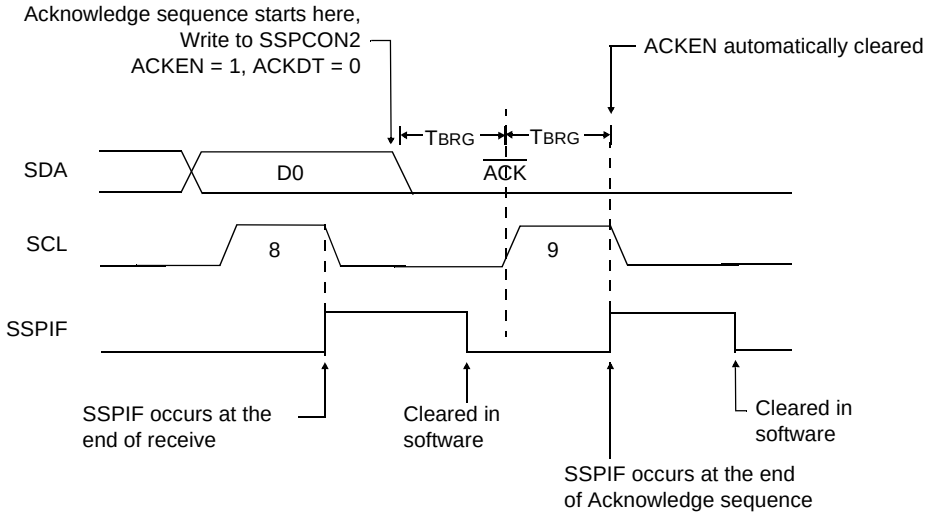
An Acknowledge sequence is enabled by setting the Acknowledge sequence enable bit, ACKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit ACKDT (SSPCON2<5>) is presented on the SDA pin. If the user wishes to generate an Acknowledge (ACK), then the ACKDT bit should be cleared. Otherwise, the user should set the ACKDT bit (NACK) before starting an Acknowledge sequence. The baud rate generator is then loaded from SSPADD<6:0> and counts for one rollover period (TBRG). The SCL pin is then de-asserted (pulled high). When the SCL pin is sampled high (clock arbitration), the baud rate generator is reloaded and counts for another TBRG. At the completion of the TBRG period, the following events occur (see Figure 9-20):

- The SCL pin is pulled low.
- The ACKEN bit is automatically cleared.
- The baud rate generator is turned off.
- The MSSP module goes into IDLE mode.

9.2.14.1 WCOL STATUS FLAG

If the user writes the SSPBUF when an Acknowledge sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 9-20: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one baud rate generator period.

11.3 Selecting the A/D Conversion Clock

The A/D conversion cycle requires 13TAD: 1 TAD for settling time, and 12 TAD for conversion. The source of the A/D conversion clock is software selected. If neither the internal VRH nor VRL are used for the A/D converter, the four possible options for TAD are:

- 2 TOSC
- 8 TOSC
- 32 TOSC
- A/D RC oscillator

If the VRH or VRL are used for the A/D converter reference, then the TAD requirement is automatically increased by a factor of 8.

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μs. Table 11-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

The ADIF bit is set on the rising edge of the 14th TAD. The GO/DONE bit is cleared on the falling edge of the 14th TAD.

TABLE 11-1: TAD VS. DEVICE OPERATING FREQUENCIES

A/D Reference Source	A/D Clock Source (TAD)		Device Frequency			
	Operation	**ADCS<1:0>**	**20 MHz**	**5 MHz**	**4 MHz**	**1.25 MHz**
External VREF or Analog Supply	2 TOSC	00	100 ns(2)	400 ns(2)	500 ns(2)	1.6 μs
	8 TOSC	01	400 ns(2)	1.6 μs	2.0 μs	6.4 μs
	32 TOSC	10	1.6 μs	6.4 μs(3)	8.0 μs(3)	25.6 μs(3)
	A/D RC	11	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)
Internal VRH or VRL	16 TOSC	00	800 ns(2)	3.2 μs(2)	4 μs(2)	12.8 μs
	64 TOSC	01	3.2 μs(2)	12.8 μs	16 μs	51.2 μs(3)
	256 TOSC	10	12.8 μs	51.2 μs(3)	64 μs(3)	204.8 μs(3)
	A/D RC	11	16 - 48 μs(4,5)	16 - 48 μs(4,5)	16 - 48 μs(4,5)	16 - 48 μs(4,5)

Legend: Shaded cells are outside of recommended range.

Note 1: The A/D RC source has a typical TAD time of 4 μs for VDD > 3.0V.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the A/D RC clock source is only recommended if the conversion will be performed during SLEEP.

5: A/D RC clock source has a typical TAD time of 32 μs for VDD > 3.0V.

TABLE 12-6: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

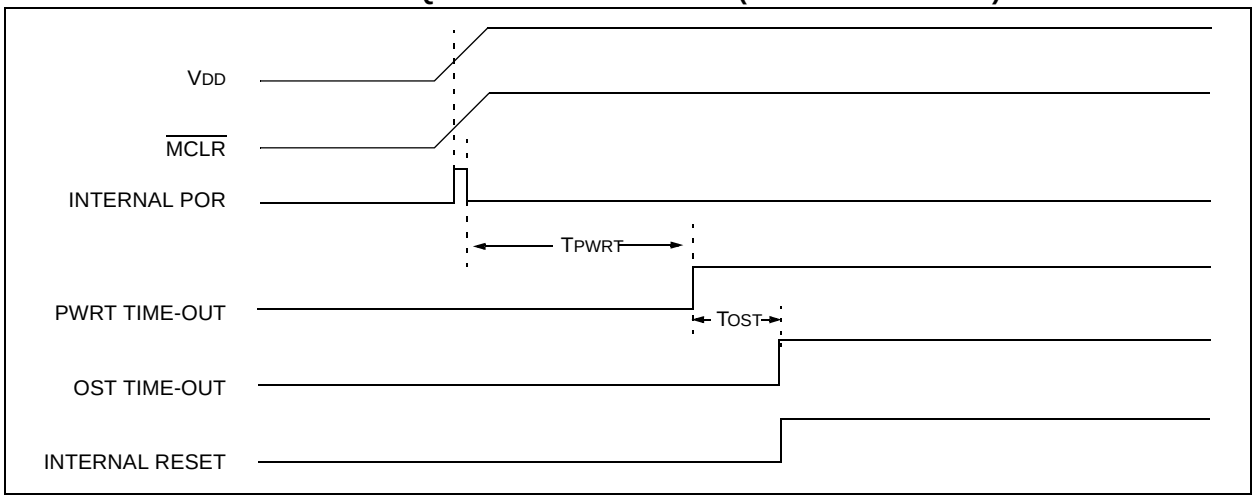
Register	Power-on Reset or Brown-out Reset	$\overline{\text{MCLR}}$ Reset or WDT Reset	Wake-up via WDT or Interrupt
P1DEL	0000 0000	0000 0000	uuuu uuuu
REFCON	0000 ----	0000 ----	uuuu ----
LVDCON	--00 0101	--00 0101	--uu uuuu
ANSEL	--11 1111	--11 1111	--uu uuuu
ADRESL	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON1	0000 0000	0000 0000	uuuu uuuu
PMDATL	xxxx xxxx	uuuu uuuu	uuuu uuuu
PMADRL	xxxx xxxx	uuuu uuuu	uuuu uuuu
PMDATH	--xx xxxx	--uu uuuu	--uu uuuu
PMADRH	---- xxxx	---- uuuu	---- uuuu
PMCON1	1--- ---0	1--- ---0	1--- ---0

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

2: See Table 12-5 for RESET value for specific condition.

FIGURE 12-6: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO V_{DD})



13.0 INSTRUCTION SET SUMMARY

Each PIC16CXXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 13-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 13-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 13-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
PC	Program Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 13-2 lists the instructions recognized by the MPASM™ assembler.

Figure 13-1 shows the general formats that the instructions can have.

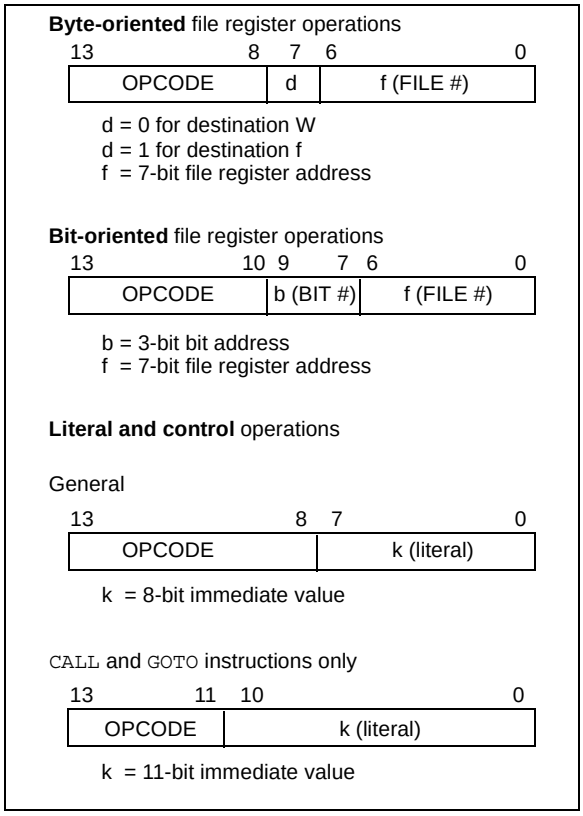
Note: To maintain upward compatibility with future PIC16CXXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 13-1: GENERAL FORMAT FOR INSTRUCTIONS



A description of each instruction is available in the PIC Mid-Range MCU Family Reference Manual, (DS33023).

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(\bar{f}) \rightarrow$ (destination)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

GOTO	Unconditional Branch
Syntax:	[*label*] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	$k \rightarrow$ PC<10:0> PCLATH<4:3> $\rightarrow$ PC<12:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two cycle instruction.

DECF	Decrement f
Syntax:	[*label*] DECF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 $\rightarrow$ (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

INCF	Increment f
Syntax:	[*label*] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 $\rightarrow$ (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

DECFSZ	Decrement f, Skip if 0
Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 $\rightarrow$ (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, then a NOP is executed instead making it a 2TCY instruction.

INCFSZ	Increment f, Skip if 0
Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 $\rightarrow$ (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead making it a 2TCY instruction.

TABLE 15-12: PIC16C770/771 AND PIC16LC770/771 A/D CONVERSION REQUIREMENTS (NORMAL MODE)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130*(3)	TAD	A/D clock period	1.6	—	—	µs	Tosc based, VREF ≥ 2.5V
			3.0	—	—	µs	Tosc based, VREF full range
							ADCS<1:0> = 11 (A/D RC mode)
			3.0	6.0	9.0	µs	At VDD = 2.5V
			2.0	4.0	6.0	µs	At VDD = 5.0V
131*	TCNV	Conversion time (not including acquisition time) **(Note 1)**	—	13TAD	—	TAD	
132*	TACQ	Acquisition Time	**Note 2**	11.5	—	µs	
			5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1LSb (i.e., 1mV @ 4.096V) from the last sampled voltage (as stated on CHOLD).
134*	TGO	Q4 to A/D clock start	—	TOSC/2	—	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 11.6 for minimum conditions.

3: These numbers multiplied by 8 if VRH or VRL is selected as A/D reference.

TABLE 15-14: PIC16C717 AND PIC16LC717 A/D CONVERTER CHARACTERISTICS:

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	10 bits	bit	Min. resolution for A/D is 4.1 mV, VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A03	EIL	Integral error	—	—	±1	LSb	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A04	EDL	Differential error	—	—	±1	LSb	No missing codes to 10 bits VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A06	EOFF	Offset error	—	—	±2	LSb	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A07	EGN	Gain Error	—	—	±1	LSb	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A10	—	Monotonicity	—	Note 3	—	—	AVSS ≤ VAIN ≤ VREF+
A20*	VREF	Reference voltage (VREF+ - VREF-)	4.096	—	VDD +0.3V	V	Absolute minimum electrical spec to ensure 10-bit accuracy.
A21*	VREF+	Reference V High (AVDD or VREF+)	VREF-	—	AVDD	V	Min. resolution for A/D is 4.1 mV
A22*	VREF-	Reference V Low (AVSS or VREF-)	AVSS	—	VREF+	V	Min. resolution for A/D is 4.1 mV
A25*	VAIN	Analog input voltage	VREFL	—	VREFH	V	
A30*	ZAIN	Recommended impedance of analog voltage source	—	—	2.5	kΩ	
A50*	IREF	VREF input current **(Note 2)**	—	—	10	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN. To charge CHOLD see Section 11.0. During A/D conversion cycle.

* These parameters are characterized but not tested.

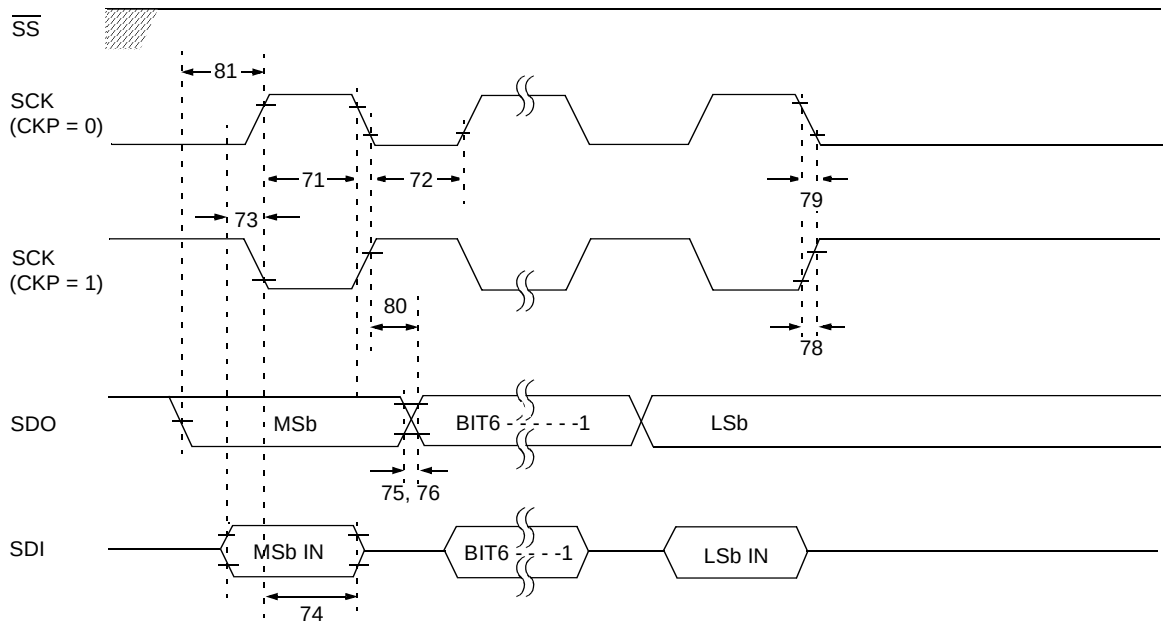
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from External VREF+, or VREF-, or AVSS, or AVDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

FIGURE 15-19: SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 15-4 for load conditions.

TABLE 15-18: SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
71*	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A*			Single Byte	40	—	—	ns	**Note 1**
72*	TscL	SCK input low time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
72A*			Single Byte	40	—	—	ns	**Note 1**
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A*	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	**Note 1**
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75*	TdoR	SDO data output rise time	PIC16**C**XXX	—	10	25	ns	
			PIC16**LC**XXX		20	45	ns	
76*	TdoF	SDO data output fall time		—	10	25	ns	
78*	TscR	SCK output rise time (Master mode)	PIC16**C**XXX	—	10	25	ns	
			PIC16**LC**XXX		20	45	ns	
79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	PIC16**C**XXX	—	—	50	ns	
			PIC16**LC**XXX		—	100	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		TCY	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.

FIGURE 16-6: TYPICAL IDD VS. FOSC OVER VDD (LP MODE)

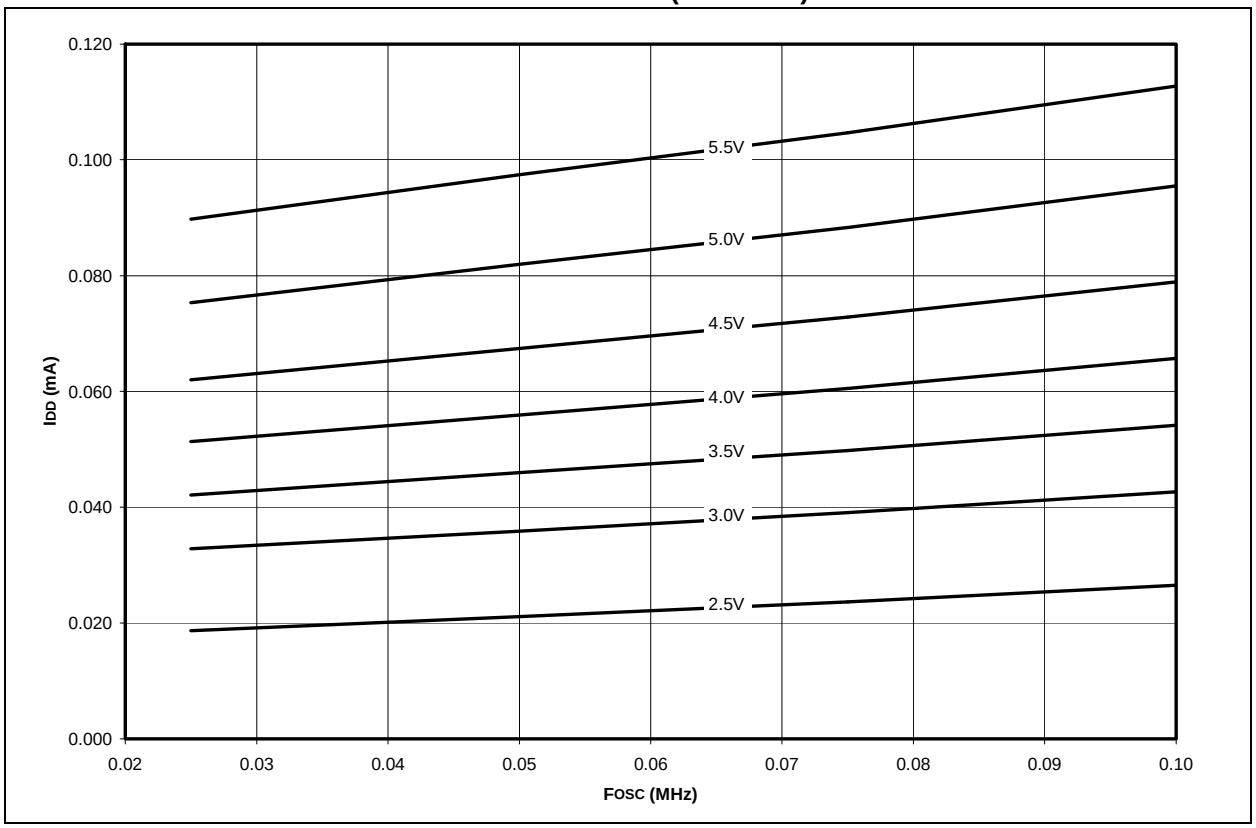
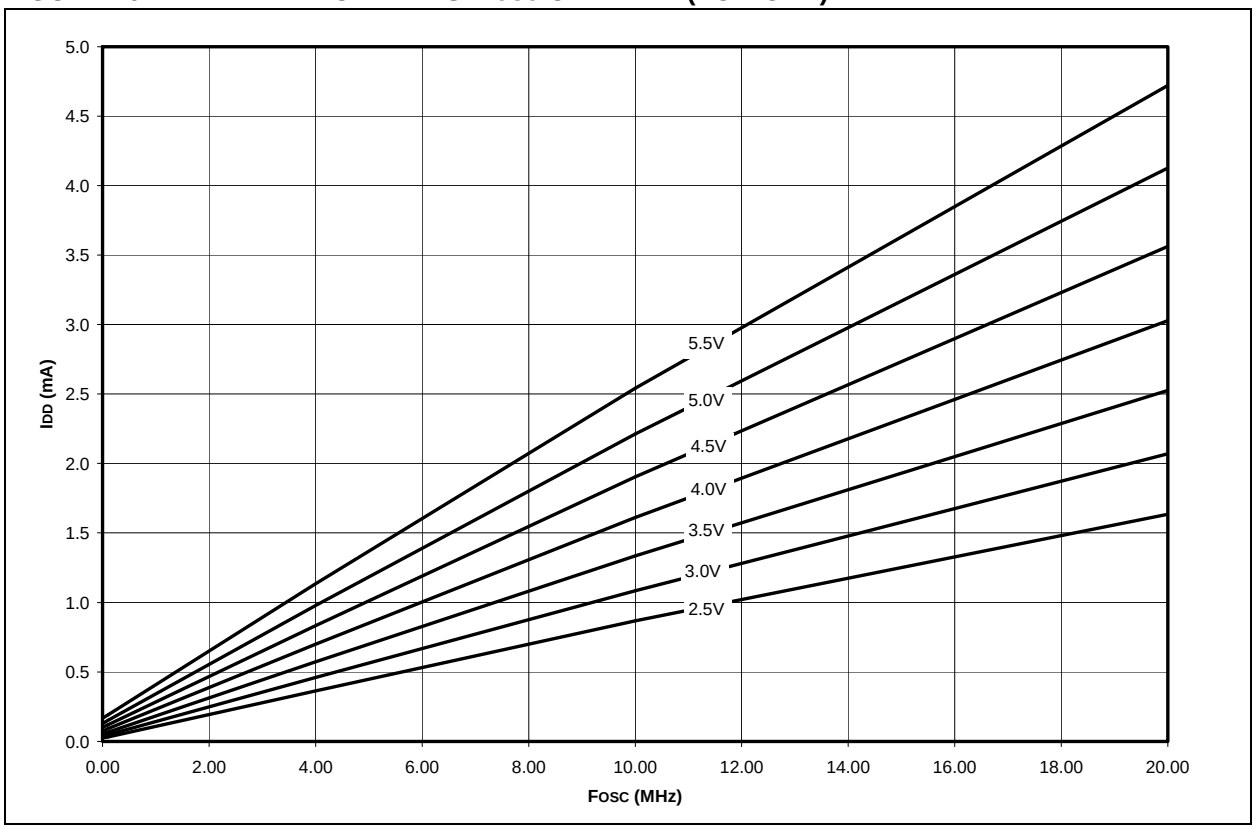
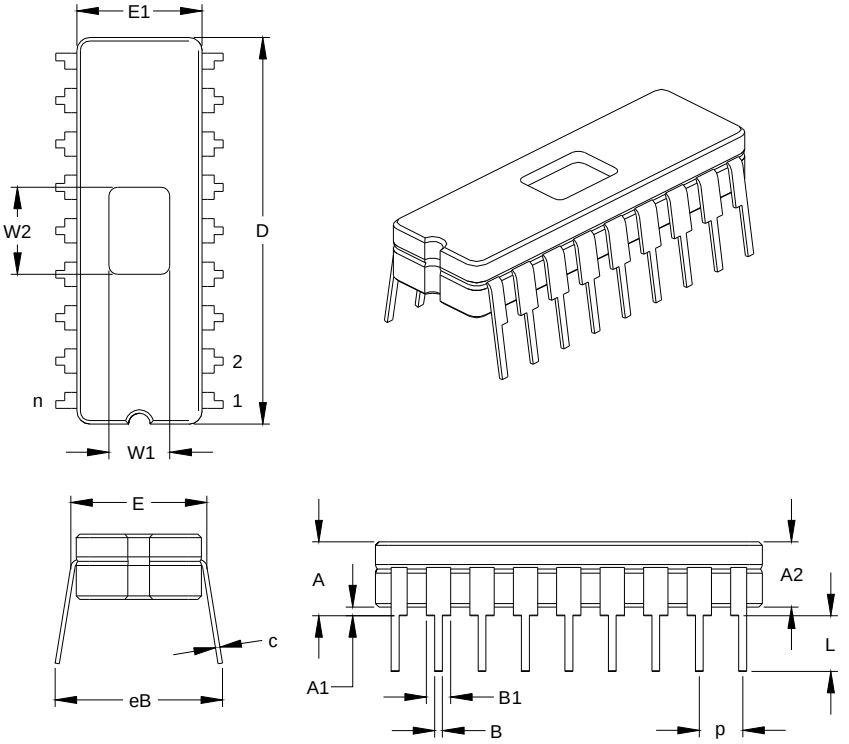


FIGURE 16-7: MAXIMUM IDD VS. FOSC OVER VDD (EC MODE)



17.3 18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

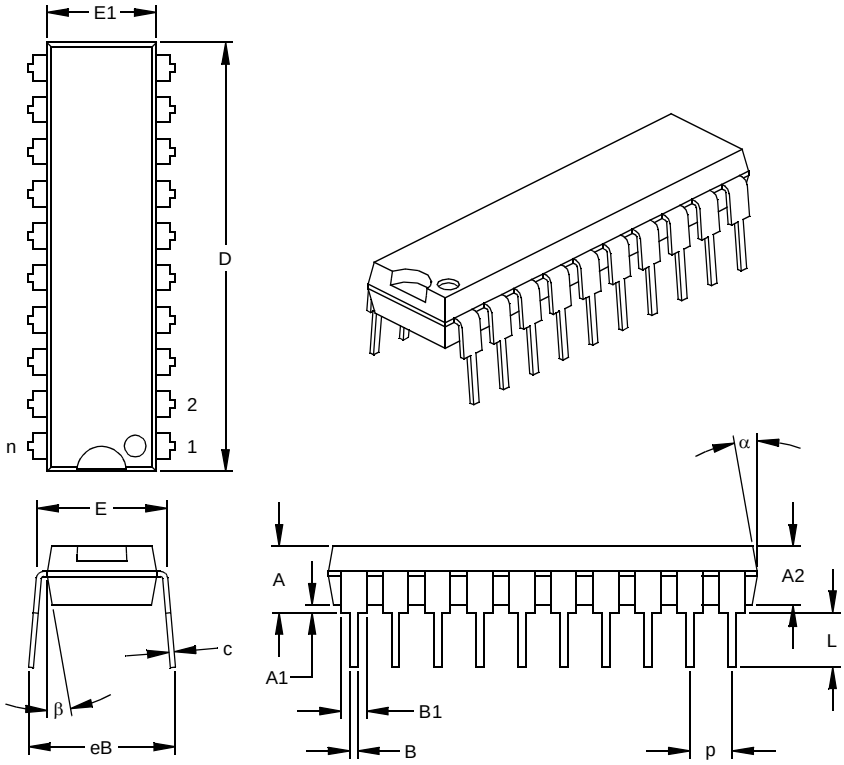


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

*Controlling Parameter
JEDEC Equivalent: MO-036
Drawing No. C04-010

17.5 20-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.295	.310	.325	7.49	7.87	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	1.025	1.033	1.040	26.04	26.24	26.42
Tip to Seating Plane	L	.120	.130	.140	3.05	3.30	3.56
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.055	.060	.065	1.40	1.52	1.65
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-019